

4-1#-01 04-24-01. 0200 #3

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Seong Min Seo, Young Suk Chung, Jong Sik Paek, Jae Hun Ku, Jae Hak Yee

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package Including Stacked Chips

Serial No.: 09/816,599 Filing Date: March 23, 2001

Examiner: Not Yet Assigned Group Art Unit: Not Yet Assigned

Docket No.: AB-1111 US

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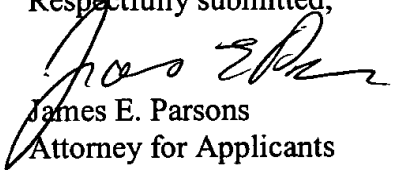
Attn: Official Draftsperson
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

SUBMISSION OF FORMAL DRAWINGS

Dear Sir:

Applicants submit 3 sheets of formal drawings, consisting of Figures 1, 2A, 2B, 3A, 3B, 4A, 4B, 5A, 5B, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (408) 453-9200.

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Respectfully submitted,

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